# A Selection Guide to ELECTRONIC MATERIALS

## from

## Dow Corning

PRODUCTS - PROPERTIES - APPLICATIONS

# Summit Distributors, Inc.

916 Main Street

**Buffalo, N. Y. 14202** 

Phone: 716-884-3450

# Selection

#### COATINGS

Dow Corning® and Sylgard® brand insulating varnishes and coatings types:

PROPERTIES		UNITS	UNITS Test Method ASTM No.		Dow Corning 997 630		
	Physical Nature (as cured)			Film	Film	Film	
	Color			Brown	Clear	Lt. Straw	
	Viscosity 25 C	centiposes	D 445	150	500	100	
	Specific Gravity 25 C		D 792	1.01	0.916	1.12	
	Shelf Life	months		12	12	12	
7	Pot Life 25 C (1)	hours		dna	dna	dna	
2	Cure Time/Temp.	hrs/°C		6/150	2/25	6/150	
E W	Refractive Index 25 C		D 1218	dna	1.4172	dna	
끙	Radiation Resistance (2)	megarads		1000	250	1000	
۵	Flash Point (open cup)	°F	D 92	90	86	105	
Z	H <sub>2</sub> O Absorption—7 days			0.40	0.10	0.15	
_	Viscosity/Temp. Coefficient			dna	dna	dna	
PHYSICAL AND CHEMICAL	Temp./Range—useful	°C		-34 to 315	-60 to 135	—34 to 260	
L S I	Thermal Conductivity	cal/cm²/°C/sec/cm		3.5 x 10-4	3.6 x 10-4	3.5 x 10-4	
Ě	Thermal Shock MIL-I-16923C	10 cycles		dna	dna	dna	
_	Weight Loss 96 hr/200 C	%		6.4	5.7	12.0	
	1000 hr/200 C	%		9.7	10.5	23.0	
	Self Extinguishing		D 635	NO	NO	NO	
	Volume Expansion	cc/cc/°C		7.0 x 10-4	8.0 x 10-4	5.9 x 10-4	
	Specific Heat 25 C	cal/gm/°C		0.34	0.33	0.34	
	Tensile Strength	psi	D 412				
	Elongation	%	D 412				
AL	Hardness Shore A	70	D 676	dna	dna	dna	
9	Pour/Brittle Point	°C	D 97/D 746	<b>—20</b>	<b>—60</b>	<b>—40</b>	
MECHANICAL	Deep Section Cure			dna	dna	dna	
<u> </u>	Bleed (MIL-I-8660)	%		dna	dna	dna	
ME	Consistency, unworked	70	D 217	dna	dna	dna	
	Evaporation	%		dna	dna	dna	
	Arc Resistance	seconds	D 495	200	180	120	
ELECTRICAL	Dielectric Constant (10 <sup>2</sup> cps)		D 924/D 150	3.1	2.8	3.4	
	Dielectric Constant (106 cps)		D 924/D 150	3.0	2.7	3.3	
	Dissipation Factor (10 <sup>2</sup> cps)		D 924/D 150	0.01	0.002	0.005	
	Dissipation Factor (106 cps)		D 924/D 150	0.007	0.001	0.002	
C	Electric Strength	volts/mil	D 877/D 149	2000	1400	2000	
ELE	Volume Resistivity	ohm-cm	D 1169/D 257	2.0 x 10 <sup>14</sup>	6.0 x 10 <sup>14</sup>	1.0 x 10 <sup>15</sup>	
	MIL SPEC.			MIL-I-2707B			

NOTES + Also available in viscosities of 10, 50, 100, 200, 350, 500 and 1,000 centistokes

dna Does not apply

\*\* Closed cup

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<sup>++</sup> Also available in viscosities of 1,000 and 10,000 centistokes

Viscosities of these fluids in centistokes

# Guide To Electronic M

POTTING AND ENCAPSULATING MATERIALS

Silastic® brand RTV adhesive type:	Dow Corning® RTV encapsulants types:						Sylgard® brand resin types:			
732	3110	3114	3116	3117	3118	3120	182	183	184	185
Rubber	Rubber	Rubber	Rubber	Rubber	Rubber	Rubber	Rubber-like	Rubber-like	Rubber-like	Rubber-l
White	White***	Buff	Tan	Tan	Buff	Red	Clear	Black	Clear	Black
700,000	12,500	12,000	50,000	50,000	30,000	30,000	5,250	8,000	5,250	8,000
1.07	1.1	1.42	1.13	1.13	1.29	1.47	1.05	1.23	1.05	1.23
6	12	6	12	12	6	12	12	12	6	6
1	3.0	4	3	10 min.	1.5	3	8	4	2	2
24/25	24/25	24/25	24/25	12/25	24/25	24/25	4/65	4/65	24/25	24/25
dna	dna	dna	dna	dna	dna	dna	1.43	dna	1.43	dna
100	100	100	100	100	100	100	200	250	200	250
dna	dna	dna	dna	dna	dna	dna	dna	dna	dna	dna
0.40	0.4	0.3	0.4	0.4	0.3	0.2	0.10	0.12	0.10	0.12
dna	dna	dna	dna	dna	dna	dna	dna	dna	dna	dna
—73 to 260	-65 to 250	-65 to 250	-65 to 250	-65 to 250	-65 to 250	-65 to 300	-65 to 200	-65 to 250	-65 to 200	—65 to 2
4.95 x 10-4	5.0 x 10-4	5.7 x 10-4	5.2 x 10-4	5.2 x 10-4	5.2 x 10-4	7.5 x 10-4	3.5 x 10-4	7.5 x 10-4	3.5 x 10-4	7.5 x 10
pass	pass	pass	pass	pass	pass	pass	pass	pass	pass	pass
6.4	6	6	6.3	6.3	2.0	5.7	2.1	1.5	2.1	1.5
							3.2	2.3	4.0	2.8
NO							YES	YES	YES	YES
9.3 x 10-4	7.5 x 10-4	7.5 x 10-4	7.5 x 10-4	7.5 x 10-4	7.8 x 10-4	5.2 x 10-4	9.6 x 10-4	7.8 x 10-4	9.6 x 10-4	7.8 x 1
0.35	0.35	0.34	0.34	0.34	0.35	0.32	0.34	0.32	0.34	0.32
200	350	400	300	300	300	650	900	900	900	900
250	150	140	160	160	150	100	100	100	100	100
25 -73	45	40	35	43	42	65	40 —70	45 —65	40 —70	45 —65
	VEC	NO	NO	NO	VEC	VEC				
NO	YES	NO	NO	NO	YES	YES	YES	YES	YES	YES
dna	dna	dna	dna	dna	dna	dna	dna	dna	dna	dna
dna	dna	dna	dna	dna	dna	dna	dna	dna	dna	dna
dna	dna	dna	dna	dna	dna	dna	dna	dna	dna	dna
50	90	120	90	90	120	125	115	130	115	130
3.0	3.00	3.60	3.00	3.00	3.50	3.8	2.75	3.05	2.75	3.05
2.9	2.9	3.45	2.9	2.9	3.3	3.7	2.60	2.75	2.60	2.75
0.015	0.015	0.020	0.015	0.015	0.020	0.050	0.001	0.007	0.001	0.007
0.005	0.005	0.008	0.005	0.005	0.003	0.003	0.001	0.01	0.001	0.01
500	600	560	600	550	525	550	550	550	550	550
1.0 x 10 <sup>13</sup>	1 x 10 <sup>14</sup>	3 x 10 <sup>14</sup>	1 x 10 <sup>14</sup>	1 x 10 <sup>14</sup>	3 x 10 <sup>14</sup>	5 x 10 <sup>13</sup>	2.0 x 10 <sup>15</sup>	1.0 x 10 <sup>14</sup>	2.0 x 1015	1.0 x 10

<sup>(1)</sup> Pot life is defined as time required to double viscosity after catalyst has been added.

All values are typical of production materials and are not intended for use in preparing specifications.

<sup>(2)</sup> Useful after exposure to this megarad dose

# aterials

COOLANTS

COMPOUNDS

Dow Corning® fluid type:

Dow Corning® compounds and lubricants types:

200	3	4 Compound	340 s	med. 33 Grease	PROPERTIES
Fluid	Grease	Grease	Grease	Grease	Physical Nature
Clear	Trans.	Trans.	White	Gray	Color
20+*	dna	dna	dna	dna	Viscosity
0.955	1.0	1.0	2.45	.972	Specific Gravity
12	12	12	12	12	Shelf Life
dna	dna	dna	dna	dna	Pot Life
dna	dna	dna	dna	dna	Cure Time/Temp.
1.40	1.406	1.406	dna	dna	Refractive Index
190	15	20	65	300	Radiation Resistance
450	dna	dna	dna	dna	Flash Point
dna	0.30	0.30	0.20	0.20	H <sub>2</sub> O Absorption
0.59	dna	dna	dna	dna	Viscosity/Temp. Coefficient
-60 to 232	—40 to 200	—57 to 200	-65 to 200	-73 to 175	Temp. Range—useful
3.4 x 10-4	5.0 x 10-4	5.0 x 10-4	10.0 x 10-4	2.8 x 10-4	Pot Life  Cure Time/Temp.  Refractive Index  Radiation Resistance  Flash Point  H <sub>2</sub> O Absorption  Viscosity/Temp. Coefficient  Temp. Range—useful  Thermal Conductivity  Thermal Shock
dna	dna	dna	dna	dna	Thermal Shock
dna	1.0	1.0	1.0	1.0	Weight Loss 96 hr/200 C
dna					1000 hr/200 C
dna	YES	YES	YES	YES	Self Extinguishing
10.7 x 10-4	9.5 x 10-4	9.5 x 10-4	7.5 x 10-4	8.0 x 10-4	Volume Expansion
0.412	0.34	0.34	0.25	0.31	Specific Heat
					The second secon
dna	dna	dna	dna	dna	Tensile Strength
dna	dna	dna	dna	dna	Elongation
dna	dna	dna	dna	dna	Hardness Shore A
60	<b>—75</b>	-80	<b>—75</b>	<b>—73</b>	Pour/Brittle Point
dna	dna	dna	dna	dna	Hardness Shore A Pour/Brittle Point Deep Section Cure Bleed
dna	3.0	4.0	0.4	2.0	Bleed
dna	200	200	290	260	Consistency
dna	1.5	1.5	0.5	1.5	Evaporation
dna	140	166	120	dna	Arc Resistance
2.68	2.85	2.85	4.9	dna	Dielectric Constant (10 <sup>2</sup> cps)
2.68	2.85	2.85	4.9	dna	Dialoghia Constant (106 and)
0.00004	0.0006	0.0006	0.005	dna	Dissipation Factor (10 <sup>2</sup> cps)
0.00001	0.0006	0.0006	0.001	dna	Dissipation Factor (10° cps)  Dissipation Factor (10° cps)  Electric Strength  Volume Resistivity
350	500	500	450	dna	Electric Strength
1.0 x 10 <sup>14</sup>	1.0 x 10 <sup>14</sup>	1.0 x 10 <sup>14</sup>	2.0 x 10 <sup>15</sup>	dna	Volume Resistivity
MIL-S-		MIL-I-		OS-	MIL SPEC.
21568A		8660A		10509	

### Dow Corning Electronic Materials

Dow Corning manufactures a complete line of dielectric materials for the electronic industry. Among these products is a wide range of silicone fluids, resins, varnishes, compounds, elastomers, molding compounds and laminating resins.

#### HEAT SHRINKABLE RUBBER

Parts and tubing of heat shrinkable silicone rubber are among the newest dielectric products available from Dow Corning. Used for cable coverings, connector boots and cable splicing, heat shrinkable rubber parts exhibit high heat resistance and good ablative properties.

#### MOLDING COMPOUNDS

Dow Corning manufacturers transfer molding compounds for the fabrication of molded parts and the encapsulation of resistors, capacitors, diodes, transistors, modules and other electronic components. Silicone molding compounds exhibit excellent properties over a temperature range of —65 to 300 C. The low dielectric losses exhibited by these materials result in extended operating frequency ranges for high frequency devices.

#### SILICONE LAMINATES

Glass laminates bonded with Dow Corning silicone resins are available through leading custom fabricators and distributors. These silicone glass laminates are used for circuit boards, coil forms, protective tubing and mechanical parts requiring high heat resistance and good high frequency dielectric performance.

#### SILICONE FLUIDS

**DOW CORNING® 331 Fluid** is a dielectric coolant for airborne electronic systems and other electronic devices. It is designed to meet MIL-S-27875.

**DOW CORNING FS-1265 Fluid** is a flurosilicone fluid with lubrication properties comparable to many organic lubricants . . . has been found especially useful for gyro floatation.

and 705 are specially formulated silicone fluids designed to produce ultrahigh vacuum. These fluids are stable, clear and exhibit low vapor pressures. Pressures of 5 x 10<sup>-11</sup> torr, or lower, are attainable when refrigerated baffles are used in conjunction with Dow Corning 705 fluid. Applications for Dow Corning fluid types 702 and 704 include vacuum deposition of films in thin film electronic circuitry and production of thermionic and cold cathode vacuum tubes.

#### PROTECTIVE COATINGS

**DOW CORNING 145** (red) and 630 (clear) **Protective Coatings** are water repellent, flexible, wax-like films that air dry after application by brush, dip or spray. Use for printed circuit boards, coils, circuit modules.

DOW CORNING

## DOW CORNING ELECTRONIC MATERIALS AVAILABLE FROM AUTHORIZED DISTRIBUTORS

#### SILICONE FLUIDS

DOW CORNING® 200 Electronic Fluid is available from authorized distributors in viscosities of 10, 20, 50, 100, 200, 350, 500 and 1,000 centistokes. This fluid, designed to meet MIL-S-21568A, is tested in accordance with Dow Corning quality control specifications for electronic grade fluids.

#### SILASTIC® Brand RTV Rubber

SILASTIC 732 RTV Rubber is ready to use as squeezed from a tube or cartridge. This adhesive/sealant bonds metals, plastics or silicone rubber; seals connectors, repairs cables, fills voids and can be used to encapsulate small electronic components.

#### **DOW CORNING® Brand RTV Encapsulants**

Six different encapsulants have been developed to provide selection of the product best suited for your application or processing requirements. They are:

- 1. DOW CORNING 3110 RTV Encapsulant is a low viscosity deep section curing compound that can be color coded.
- 2. DOW CORNING 3114 RTV Encapsulant is a low viscosity general purpose compound.
- 3. DOW CORNING 3116 RTV Encapsulant is a medium viscosity general purpose compound.
- 4. DOW CORNING 3117 RTV Encapsulant is a medium viscosity fast curing (10 minutes) compound.
- 5. DOW CORNING 3118 RTV Encapsulant is a medium viscosity deep section curing reversion resistant compound.
- 6. DOW CORNING 3120 RTV Encapsulant is a medium viscosity deep section curing, high strength (650 psi tensile) compound.

#### SLYGARD® Brand SOLVENTLESS SILICONE RESINS

**SYLGARD 182 Resin** is a transparent silicone resin for potting, encapsulating and coating electronic circuits and components. Long pot life and low viscosity make this elevated temperature curing material ideal for use in production dispensing equipment.

**SYLGARD 183 Resin,** companion product to Sylgard 182 resin, is an opaque material with better heat conduction and a wider serviceable temperature range.

**SYLGARD 184 Resin,** a transparent room temperature curing resin, is designed for the potting and encapsulation of heat sensitive devices and circuits.

SYLGARD 185 Resin, opaque version of Sylgard 184 resin, is used where opacity is an asset and higher heat conductance is required.

#### SILICONE COMPOUNDS

DOW CORNING 3 Compound is a translucent, grease-like material, designed to reduce corrosion on switch contacts and battery terminals and as an insulator for electronic assemblies.

DOW CORNING 4 Compound, a greaselike sealing and lubricating material for switches, toroids and connectors and a moisture proofer for electronic equipment, is designed to meet MIL-I-8660A.

**DOW CORNING 340 Compound** is a highly heat conductive, greaselike material used on transistor and rectifier heat sink junctions to improve thermal conduction.

#### MOLD RELEASES

DOW CORNING 7 Compound, a mold release agent, with the consistency of petroleum jelly, provides easy release of epoxies, polyesters and vinyls.

**DOW CORNING 20 Compound** is a heat curing mold release agent designed to form a durable thin film for easy release of epoxies, polyurethane foams, silicone laminates and silicone encapsulating resins.

#### **LUBRICANTS**

**DOW CORNING 33 Grease,** in medium and light consistencies, is designed to lubricate ball bearings and instrument bearings over the wide temperature range of  $-100 \, \text{F}$  to 350 F. Designed to meet OS-10509.

#### COATINGS

**DOW CORNING 991 Varnish** is an air dry varnish for coating and impregnating coils, transformers and electronic circuitry.

DOW CORNING 997 Varnish meets class H insulation requirements. A high temperature material, it is used for impregnating and coating coils, transformers, and other electrical/electronic equipment operating in high heat environments. Designed to meet MIL-I-2707B.

**SYLGARD 1377 Varnish**, a general purpose varnish with excellent adhesion and moisture resistance, is designed for coating and impregnating coils, transformers and reactors. Meets requirements of A, B, F, and H insulation systems.

Additional information on any or all of these materials is available from the Electronic Products Division, Dow Corning Corporation, Midland, Michigan, 48641.

ELECTRONIC PRODUCTS DIVISION, DOW CORNING CORPORATION, MIDLAND, MICHIGAN 48641

Printed in U.S.A.